

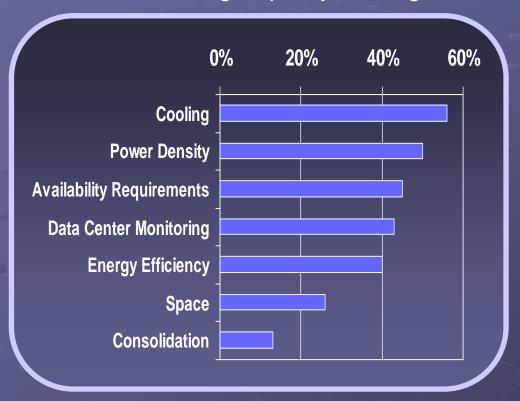
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Green IT - #1 IT Issue

Power and Cooling Capacity Limiting Growth



Source: Liebert Data Center User Group, Spring 2008



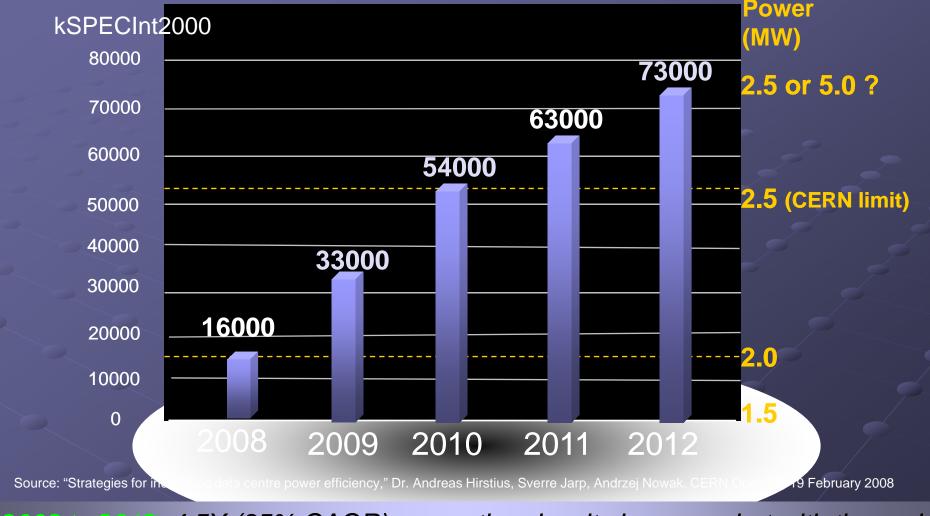
"Intel and Google Join with Dell, EDS, EPA, HP, IBM, Lenovo, Microsoft, PG&E, World Wildlife Fund and Others to Launch Climate Savers Computing Initiative"

- Intel News Release, June 12, 2007

Energy Costs and Cooling #1 Growth Limiters...



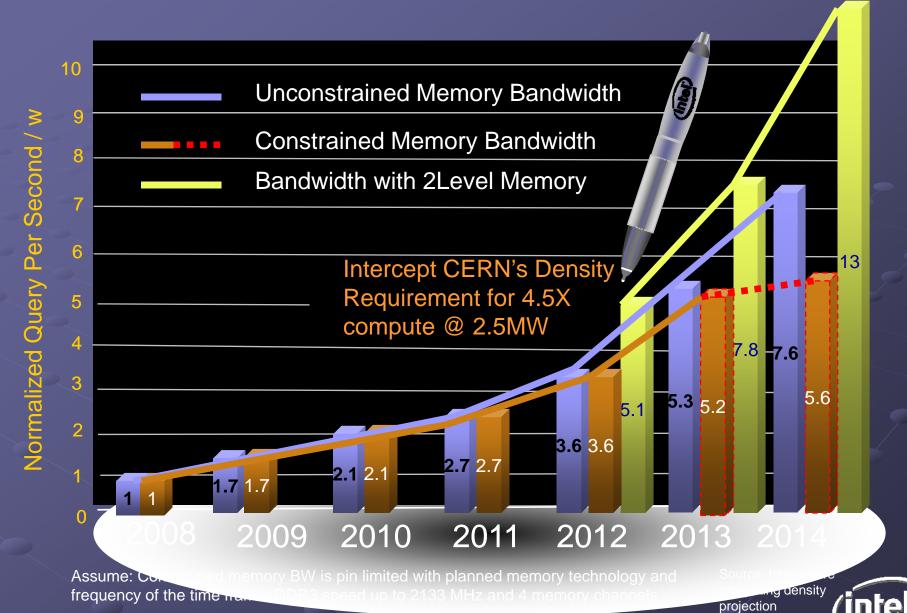
CERN's Projected Computing Need vs. Power Density



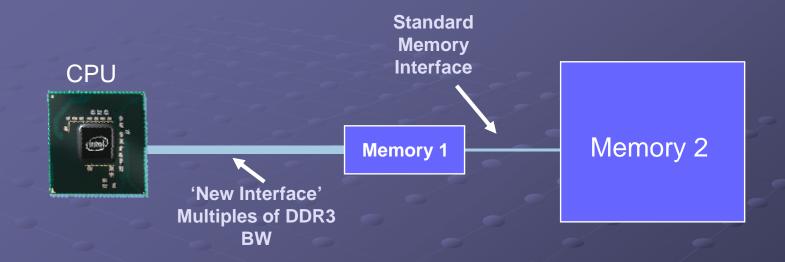
2008 to 2012: 4.5X (35% CAGR) computing density increase, but with thermal limit of 2.5 MW to possible 5 MW (requires new facility)



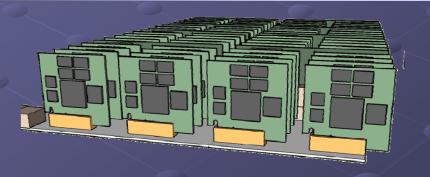
Limitations Driving Server Compute Improvements



Technology Concepts



2Level memory provides potential TCO improvement



30-40W Low Power µBlade concept

High density solutions for scale out workloads



Data Center Innovations



Containerized data centers



High density data centers



Innovations to Increase Compute Density



Silicon Process



New Technology



Small Form Factor



Power Management



Data Center Innovation

Compute Density



Year

Target 50% yearly improvements in performance/watt

Source: Intel, based on Intel YoY improvement with SpecPower Benchmark

Datacenter of the Future



Backup

